

# MOS FIELD EFFECT TRANSISTOR

3SK242

# RF AMPLIFIER AND MIXER FOR VHF TV TUNER N-CHANNEL SI DUAL GATE MOS FIELD-EFFECT TRANSISTOR 4 PINS SUPER MINI MOLD

#### **FEATURES**

• Low Noise Figure: NF = 1.3 dB TYP.

High Power Gain: G<sub>ps</sub> = 24 dB TYP. (f = 200 MHz)
 Suitable for use as RF amplifier in VHF TV tuner.
 Small Package: 4 Pins Super Mini Mold

#### **ORDERING INFORMATION**

PART NUMBER	QUANTITY	PACKING STYLE
3SK242-T1	3 Kpcs/Reel.	Embossed tape 8 mm wide. Pin3 (Gate2), Pin4 (Gate1) face to perforation side of the tape.
3SK242-T2	3 Kpcs/Reel.	Embossed tape 8 mm wide. Pin1 (Source), Pin2 (Drain) face to perforation side of the tape.

 Please contact with responsible NEC person, if you require evaluation sample. Unit sample quantity shall be 50 pcs. (Part No.: 3SK242)

## ABSOLUTE MAXIMUM RATINGS (TA = 25 $^{\circ}$ C)

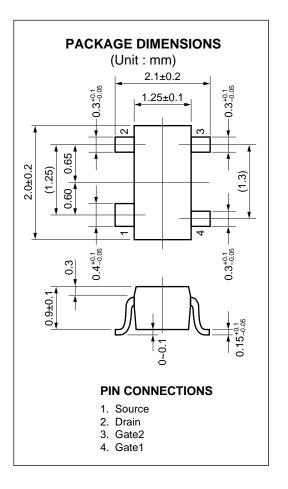
Drain to Source Voltage	VDSX	20	V
Gate1 to Source Voltage	V <sub>G1</sub> S	±8	V
Gate2 to Source Voltage	V <sub>G2</sub> S	±8	V
Drain Current	lο	25	mΑ
Total Power Dissipation	PD	130 <sup>*1</sup> /250 <sup>*2</sup>	mW
Channel Temperature	Tch	125	°C
Storage Temperature	Tstg	-55 to +125	°C



<sup>\*2: 15</sup> mm  $\times$  15 mm  $\times$  1.2 mm board by epoxy glass

### **PRECAUTION**

Avoid high static voltages or electric fields so that this device would not suffer from any damage due to those voltage or fields.





# ELECTRICAL CHARACTERISTICS (TA = 25 $^{\circ}$ C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	
Drain to Source Breakdown Voltage	BV <sub>DSX</sub>	20			V	$V_{G1S} = V_{G2S} = -2 \text{ V}, I_D = 10 \mu\text{A}$	
Drain Current	IDSS	7.0		25	mA	VDS = 6 V, VG2S = 3 V, VG1S = 0	
Gate1 to Source Cutoff Voltage	V <sub>G1S(off)</sub>			-2.0	V	$V_{DS} = 8 \text{ V}, V_{G2S} = 0$ , $I_{D} = 5 \mu A$	
Gate2 to Source Cutoff Voltage	V <sub>G2S(off)</sub>			-1.5	V	$V_{DS} = 8 \text{ V}, V_{G1S} = 0, I_{D} = 5 \mu A$	
Gate1 Reverse Current	I <sub>G1SS</sub>			±20	nA	VDS = 0, VG2S = 0, VG1S = ±8 V	
Gate2 Reverse Current	I <sub>G2</sub> ss			±20	nA	VDS = 0, VG1S = 0, VG2S = ±8 V	
Forward Transfer Admittance	yfs	22	28		mS	V <sub>DS</sub> = 6 V, V <sub>G2S</sub> = 3 V, I <sub>D</sub> = 10 mA f = 1 kHz	
Input Capacitance	Ciss	4.0	5.0	6.5	pF	V <sub>DS</sub> = 6 V, V <sub>G2S</sub> = 3 V, I <sub>D</sub> = 10 mA f = 1 MHz	
Output Capacitance	Coss	2.2	2.9	3.7	pF		
Reverse Transfer Capacitance	Crss		0.05	0.08	pF		
Power Gain	Gps	21	24		dB	V <sub>DS</sub> = 10 V, V <sub>G2S</sub> = 5 V, I <sub>D</sub> = 10 mA f = 200 MHz	
Noise Figure	NF		1.3	2.5	dB		

## **IDSX Classification**

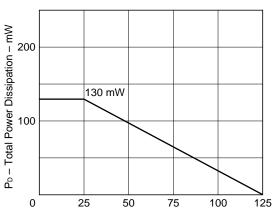
Rank	V11/VAA*	V12/VAB*	V13/VAC*
Marking	V11	V12	V13
IDSS (mA)	7.0 to 13.0	11.0 to 19.0	17.0 to 25.0

<sup>\*</sup> Old Specification / New Specification

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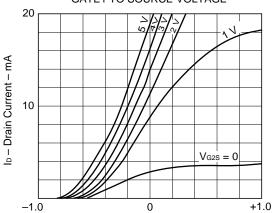
#### TYPICAL CHARACTERISTICS (TA = 25 °C)





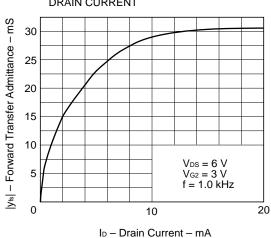
T<sub>A</sub> – Ambient Temperature – °C

#### DRAIN CURRENT vs. GATE1 TO SOURCE VOLTAGE

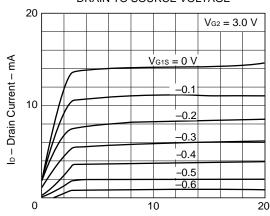


V<sub>G1S</sub> - Gate1 to Source Voltage - V

# FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

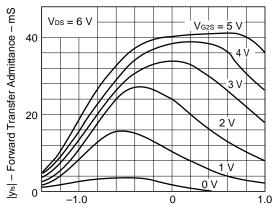


DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



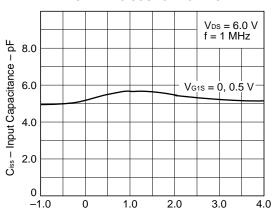
V<sub>DS</sub> - Drain to Source Voltage - V

# FORWARD TRANSFER ADMITTANCE vs. GATE1 TO SOURCE VOLTAGE



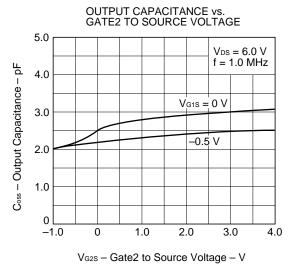
V<sub>G1S</sub> - Gate1 to Source Voltage - V

#### INPUT CAPACITANCE vs. GATE2 TO SOURCE VOLTAGE

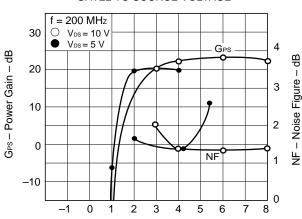


V<sub>G2S</sub> - Gate2 to Source Voltage - V



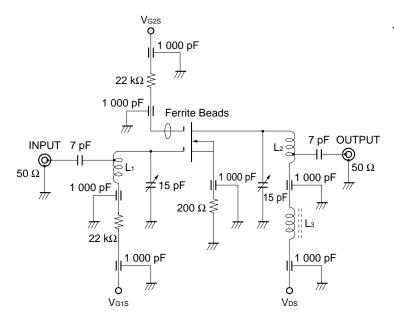


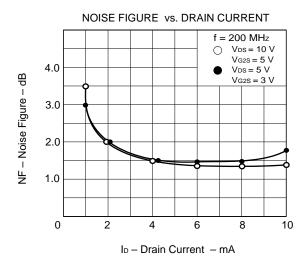
NOISE FIGURE, POWER GAIN vs. GATE2 TO SOURCE VOLTAGE



Gps AND NF TEST CIRCUIT AT f = 200 MHz

V<sub>G2S</sub> - Gate2 to Source Voltage - V





#### **TEST CONDITION**

 $V_{\text{DS}} = 10 \text{ V}, \text{ V}_{\text{G2S}} = 5 \text{ V}, \text{ I}_{\text{D}} = 10 \text{ mA}$ 

f = 200 MHz

L<sub>3</sub>: RFC 2.2  $\mu$ H

[MEMO]

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Anti-radioactive design is not implemented in this product.

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